

Automotive MOSFET

OptiMOS™ 7 Power-Transistor







Features

- OptiMOS[™] power MOSFET for automotive applications
- N-channel Enhancement mode Logic Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- · RoHS compliant
- 100% Avalanche tested



General automotive applications.

Product Validation

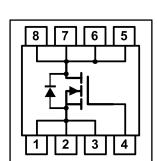
Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	40	V
R _{DS(on)}	3.05	mΩ
I _D (chip limited)	100	Α

Туре	Package	Marking
IAUZN04S7L030	PG-TSDSON-8-44	41





IAUZN04S7L030



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Maximum Ratings

at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	$V_{\rm GS} = 10 \text{ V}$, Chip limitation ^{1,2)}	100	А
		V _{GS} = 10 V, DC current	60	
		$T_a = 100^{\circ}\text{C}, V_{GS} = 10 \text{ V}, R_{thJA}$ on $2s2p^{2,3)}$	18	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_{\rm C}$ = 25°C, $t_{\rm p}$ = 100 μ s	250	1
Avalanche energy, single pulse ²⁾	E _{AS}	I _D = 24 A	40	mJ
Avalanche current, single pulse	I _{AS}	-	47	А
Gate source voltage	V_{GS}	-	±16	V
		Limited to duty factor of 1%	+20	1
Power dissipation	P_{tot}	T _C = 25°C	58	W
Operating temperature	$T_{\rm j}$	-	-55 +175	°C

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Thermal Characteristics²⁾

Paramatan	Sumbal Candikiana	Values				
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	_	_	2.6	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	-	-	41	-	

Electrical Characteristics

at T_i=25 °C, unless otherwise specified

Parameter	Suma had	Symbol Conditions	Values			l
	Symbol		min.	typ.	max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(Br)DSS}	$V_{GS} = 0 \text{ V},$ $I_D = 1 \text{ mA}$	40	-	-	V
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 15 \mu\text{A}$	1.2	1.5	1.8	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^{\circ}\text{C}$	_	_	1	μΑ
Zero gate voltage drain current	/ _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V},$ $T_j = 100^{\circ}\text{C}^{2}$	_	_	4	
Gate-source leakage current	I _{GSS}	$V_{GS} = 16 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA
		$V_{\rm GS} = 4.5 \text{V}, I_{\rm D} = 30 \text{A}$	-	3.82	4.48	mΩ
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	-	2.73	3.05]
Gate resistance ²⁾	R _G	-	-	1.2	-	Ω

IAUZN04S7L030



Parameter	Cumbal	Symbol Conditions	Values			llmit.
	Symbol		min.	typ.	max.	Unit
Dynamic Characteristics ²⁾						
Input capacitance	Ciss		_	1214	1578	pF
Output capacitance	C oss	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	_	606	788	
Reverse transfer capacitance	C rss		_	24	36	
Turn-on delay time	t _{d(on)}		_	3	-	ns
Rise time	t _r	$V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = 30 \text{ A}, R_{G} = 3.5 \Omega$	_	3	-	
Turn-off delay time	t _{d(off)}		_	12	_	
Fall time	t _f		_	9	_	

Gate Charge Characteristics2)

	_					
Gate to source charge	Q _{gs}		-	3.4	4.4	nC
Gate to drain charge	Q _{gd}	$V_{DD} = 20 \text{ V}, I_D = 30 \text{ A},$	-	3.2	4.8	
Gate charge total	Qg	$V_{DD} = 20 \text{ V}, I_D = 30 \text{ A},$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	-	18	23	
Gate plateau voltage	V _{plateau}		-	2.8	-	V

Reverse Diode

Diode continuous forward current ²⁾	Is	T _C = 25°C	ı	ı	60	А
Diode pulse current ²⁾	I _{S,pulse}	$T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 100 \mu{\rm s}$	ı	ı	250	
Diode forward voltage	V _{SD}	$V_{GS} = 0 \text{ V}, I_F = 30 \text{ A}, T_j = 25^{\circ}\text{C}$	ı	0.8	0.95	V
Reverse recovery time ²⁾	t _{rr}	V _R = 20 V, I _F = 50 A	-	16	24	ns
Reverse recovery charge ²⁾	Q _{rr}	$di_F/dt = 100 A/\mu s$	_	3	6	nC

 $^{^{1)}}$ Practically the current is limited by the overall system design including the customer-specific PCB.

²⁾ The parameter is not subject to production testing – specified by design.

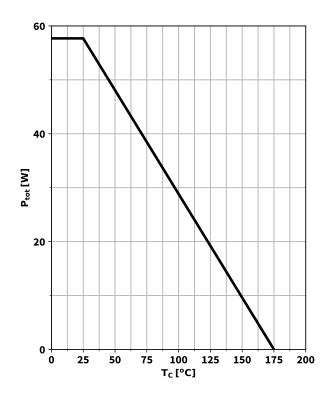
 $^{^{3)}}$ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.



Electrical characteristics diagrams

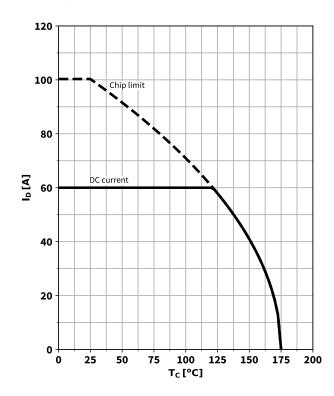
1 Power dissipation

 $P_{\text{tot}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$



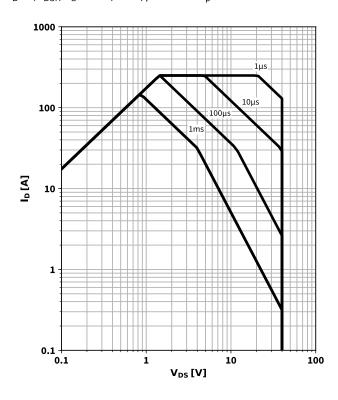
2 Drain current

 $I_{\text{D}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$



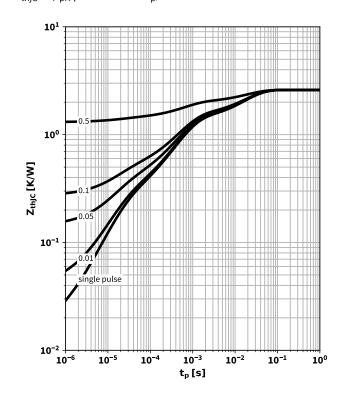
3 Safe operating area

 $I_{\rm D}$ = f($V_{\rm DS}$); $T_{\rm C}$ = 25 °C; D = 0; parameter: $t_{\rm p}$



4 Max. transient thermal impedance

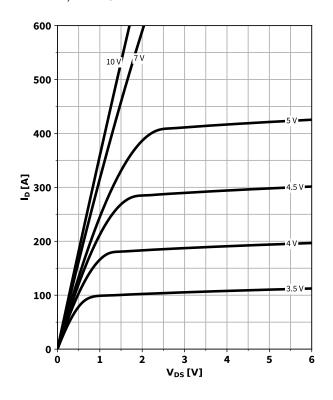
 $Z_{\text{thJC}} = f(t_p)$; parameter: D = t_p/T





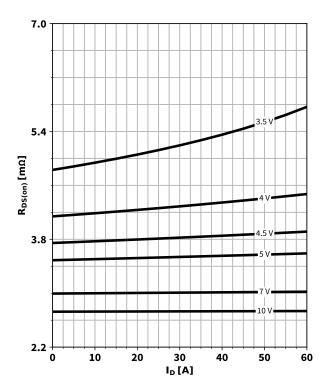
5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25 \,^{\circ}\text{C}; \text{ parameter: } V_{GS}$



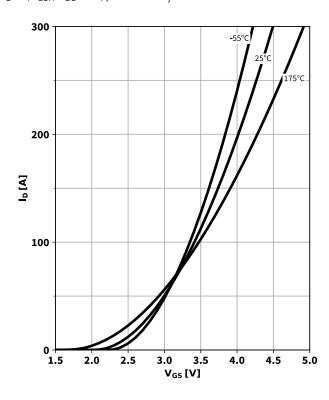
6 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(I_D); T_j = 25 \text{ °C}; parameter: } V_{GS}$



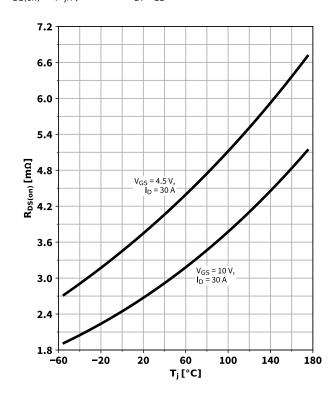
7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = 6 \text{ V}; \text{ parameter: } T_j$



8 Typ. drain-source on-state resistance

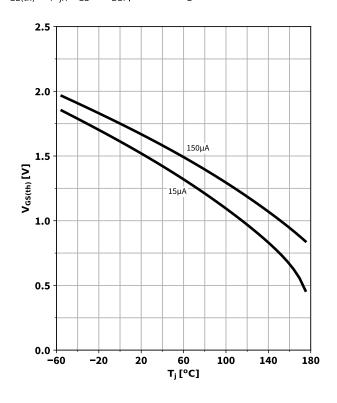
 $R_{DS(on)} = f(T_j)$; parameter: I_D , V_{GS}





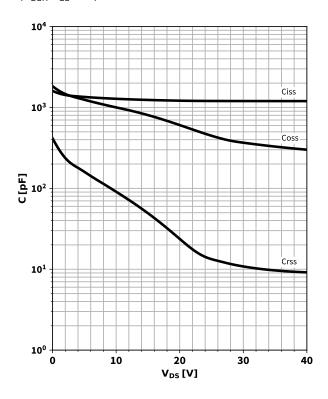
9 Typ. gate threshold voltage

 $V_{\text{GS(th)}} = f(T_{\text{j}}); V_{\text{GS}} = V_{\text{DS}}; \text{ parameter: } I_{\text{D}}$



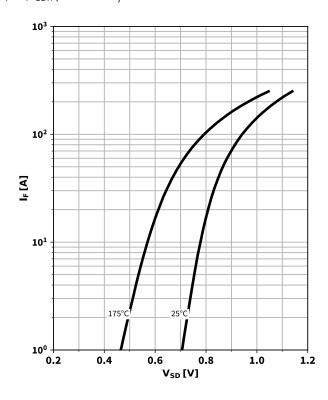
10 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



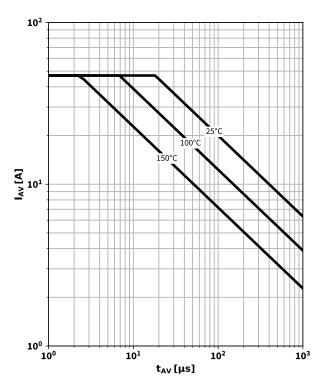
11 Typ. forward diode characteristics

 $I_F = f(V_{SD})$; parameter: T_j



12 Typ. avalanche characteristics

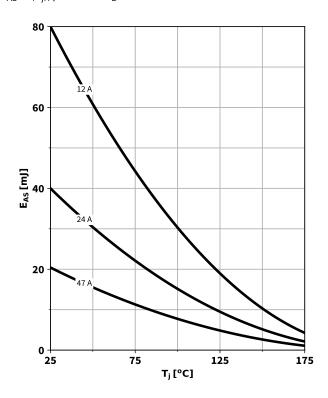
 $I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$





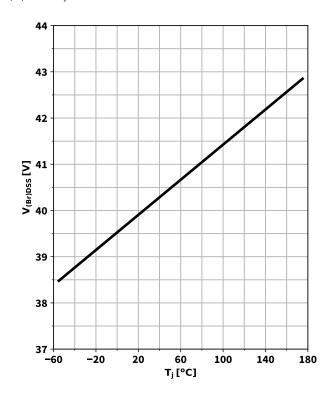
13 Typical avalanche energy

 $E_{AS} = f(T_j)$; parameter: I_D



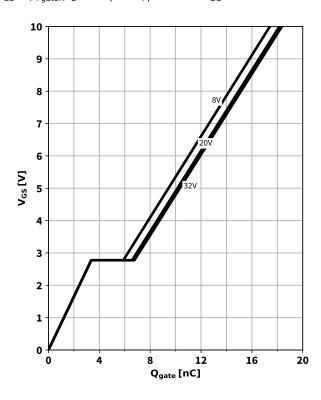
14 Drain-source breakdown voltage

 $V_{(Br)DSS} = f(T_j); I_D = 1 \text{ mA}$

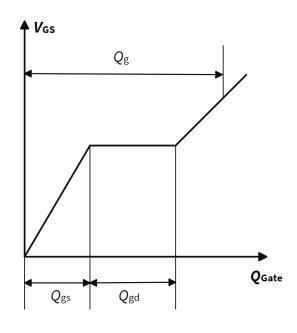


15 Typ. gate charge

 $V_{GS} = f(Q_{gate}); I_D = 30 \text{ A pulsed}; parameter: } V_{DD}$



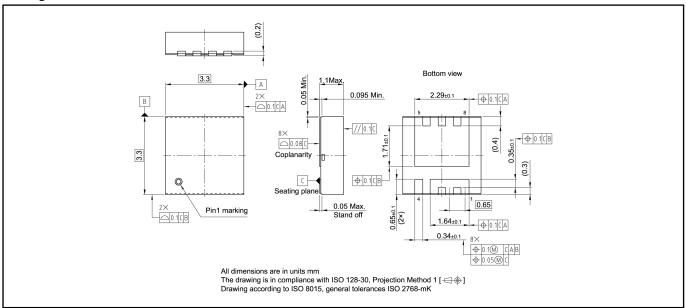
16 Gate charge waveforms



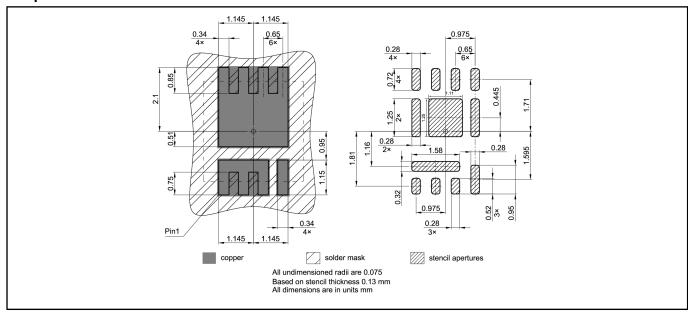
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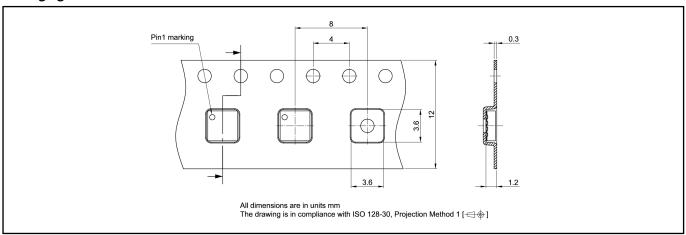
Package Outline



Footprint



Packaging



IAUZN04S7L030



Revision History

Revision	Date	Changes
Revision 1.0	2025-04-08	Final Data Sheet

Trademarks

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